

# Autoregressive DRL for Multi-Robot Scheduling in Semiconductor Cluster Tools

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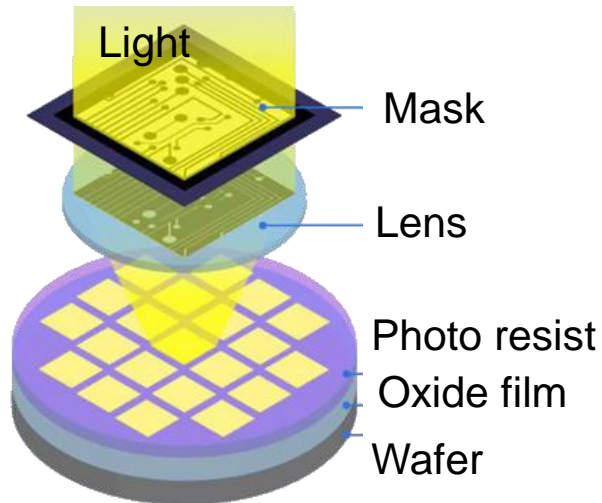
Korea University

## Semiconductor manufacturing involves multi-step processes

– e.g., photolithography, etching, cleaning, deposition

### Pattern Drawing Process in Front-end Process

Photolithography → Etch → Clean



Draw circuits on the wafer



Radial-type Cluster tool



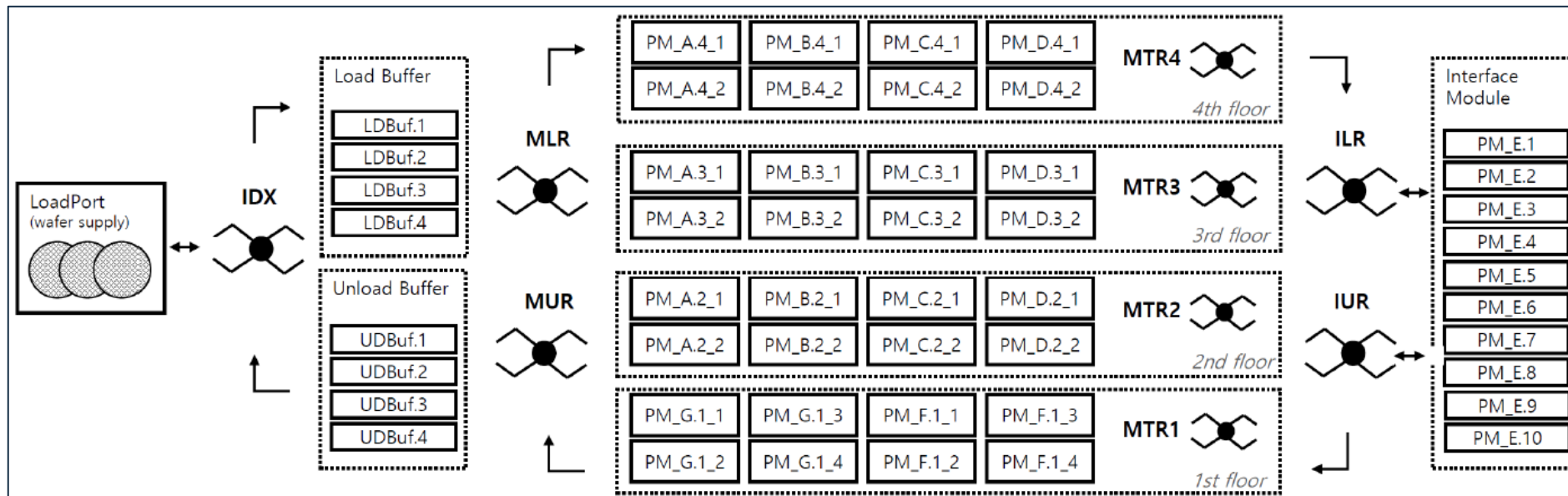
Track-type Cluster Tool



Robot

## Problem Statement

- Two distinct cluster tool environments with different layouts and robot configurations
- Goal: Learn a scheduling policy that adapts to each environment to maximize throughput



Environment B

Env B (Track)	
	9 (MTRs, ILR/U, MLR/U)
	49
	4-floor rail system
	Coordination across floors

# CORE IDEAS OF OUR APPROACH

## 1. Autoregressive Action Selection

Select robot actions one by one, not jointly.

- Reduces per-step action space
- Enables scaling to many robots

## 2. Action Masking

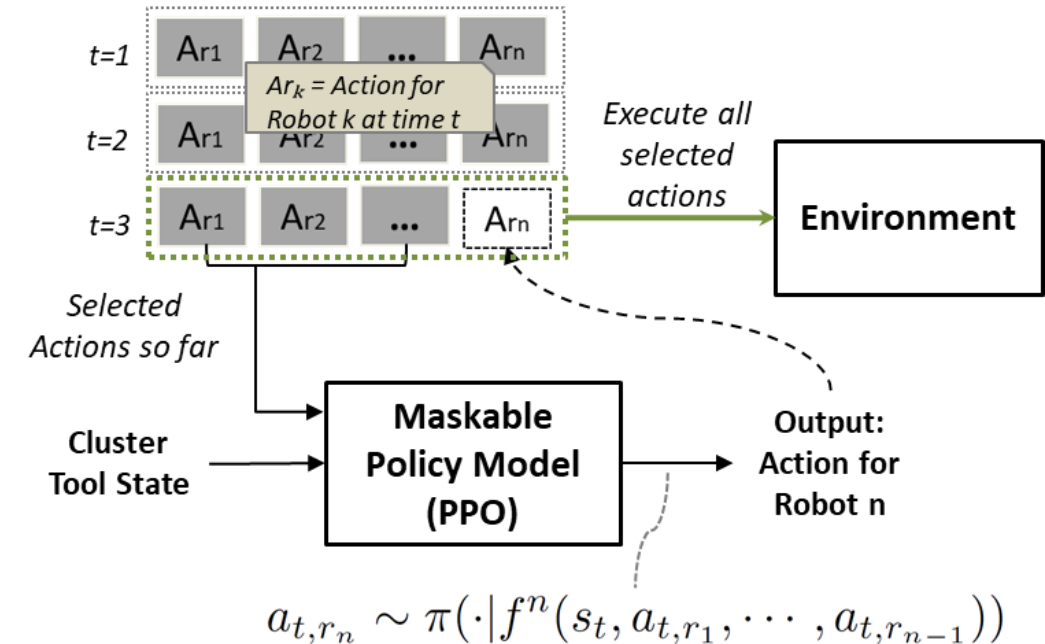
Dynamically mask out invalid actions at each step.

- Improves learning stability
- Helps focus on feasible decisions only

## 3. Reward Shaping

Combine sparse and dense rewards to guide behavior.

- Penalize idle moves and unproductive actions
- Encourage parallel processing and better throughput



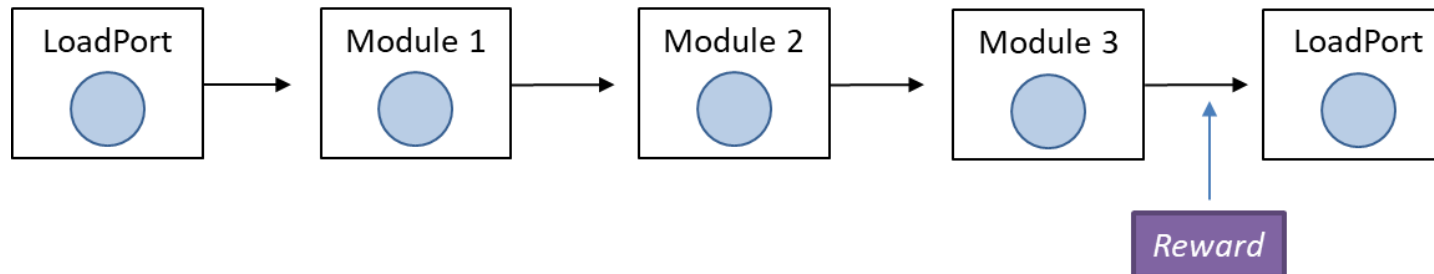
	Joint	AR (Ours)
Decision Complexity	$\mathcal{O}(\prod_i  \mathcal{A}_{r_i} )$	$\mathcal{O}(\sum_i  \mathcal{A}_{r_i} )$
Env A Action Count	216	35
Env B Action Count	$4.4 \times 10^{13}$	302

## Objective

- Maximize UPEH (Units Per Equipment Hour)
- Provide both sparse but precise and dense but guiding rewards

### 1. Completion Reward

- $r_t = \underline{k_1 \cdot r_t^{\text{completion}}} + k_2 \cdot r_t^{\text{progress}} - k_3 \cdot r_t^{\text{idle}}$
- +1 when a wafer finishes all processes and returns to the load port
- Sparse but directly aligns with the optimization goal (UPEH)



## 2. Wafer Progress Reward

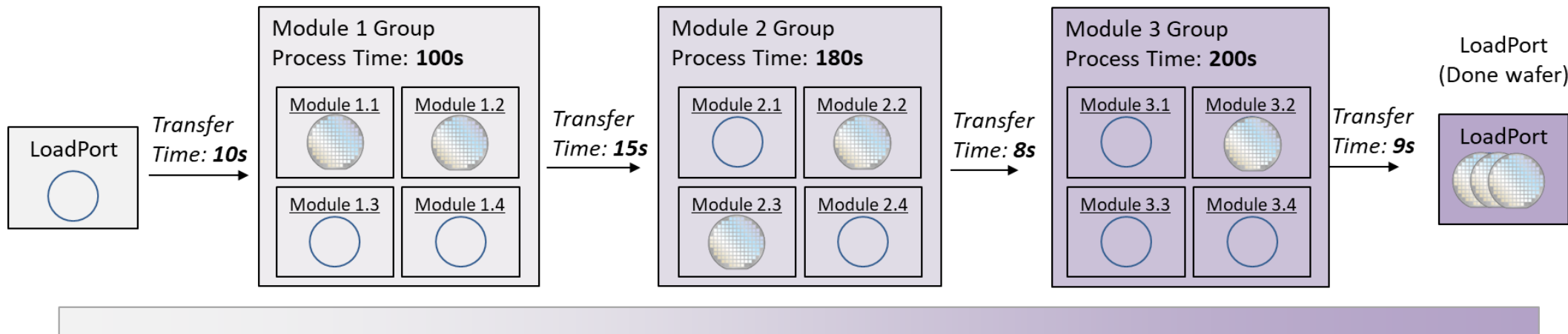
- $r_t = k_1 \cdot r_t^{\text{completion}} + k_2 \cdot r_t^{\text{progress}} - k_3 \cdot r_t^{\text{idle}}$
- A dense reward that quantifies how far each wafer has progressed through its processing path.

$$P_t = \sum_{m \in \mathcal{M}} (w_m + \tau_m)$$

$$r_t^{\text{progress}} = P_t - P_{t-1}$$

$W_m$  is the ideal time to reach module  $m$  without any delays based on physical layout, process time, robot speed, travel distance

$P_t$  is Cumulative wafer progress at time  $t$

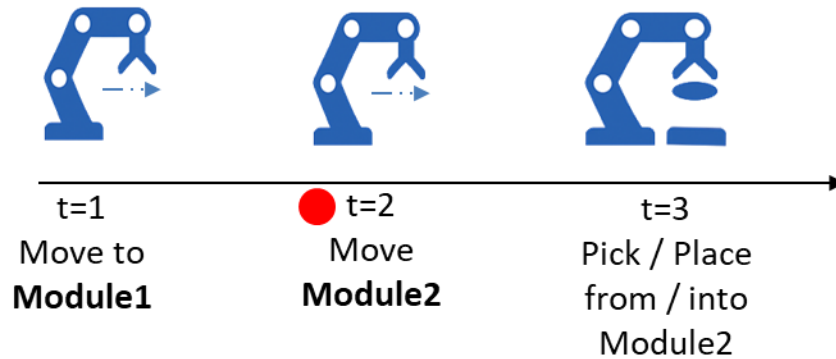


Example of Per-Step Wafer Progress Reward  $w_m$

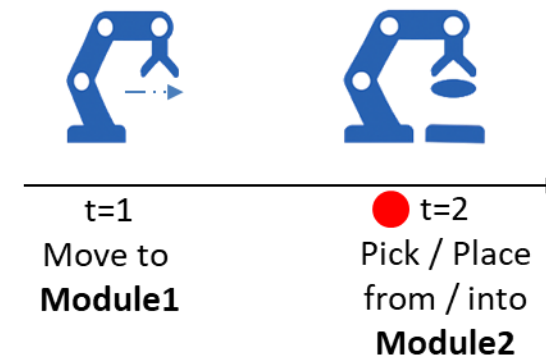
## 3. Idle Move Penalty

- $r_t = k_1 \cdot r_t^{\text{completion}} + k_2 \cdot r_t^{\text{progress}} - k_3 \cdot r_t^{\text{idle}}$
- Negative reward for movement actions that do not result in pick/place  
→ Discourages unnecessary robot movements

Example:



Case1: Idle Move



Case2: Penalty for unaligned move and action

● : Idle move penalty triggered



## Learning Convergence

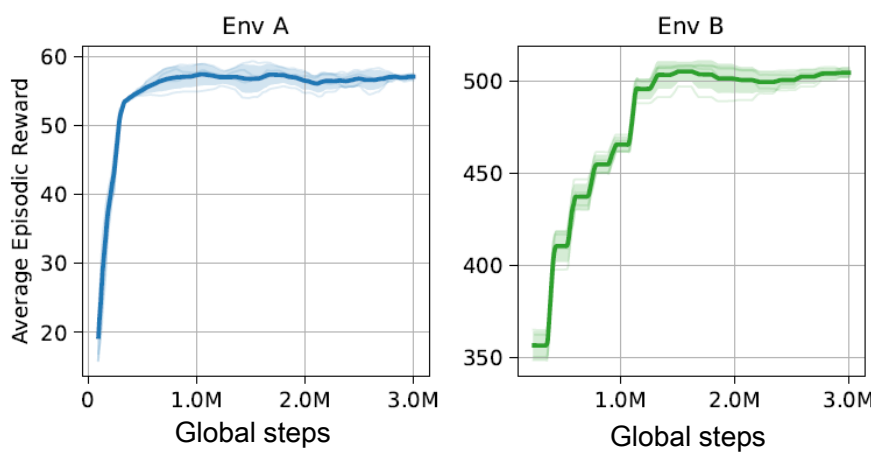
- Stable training curves in Env A & B
- Adaptive policy learned from scratch

## Throughput Comparison

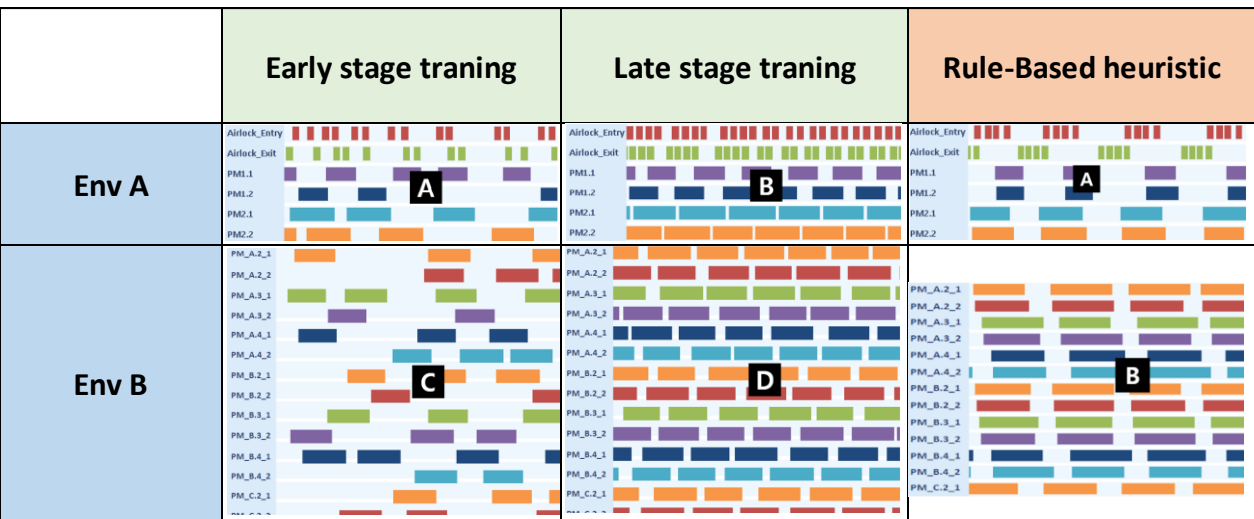
- Higher UPEH than heuristic baseline in both environments

Environment	Ours	Rule-Based
Env A	96 ± 5	58
Env B	304 ± 1	276

UPEH comparison: Ours vs. rule-based



Training curve showing convergence of average episode reward



Gantt chart visualizations of wafer processing: early vs. late training (DRL) and rule-based



## Ablation Study – Reward Composition

- Completion reward alone is sparse and insufficient
- Progress reward accelerates learning but lacks final alignment
- Combined rewards yield the best UPEH in both Env A and B

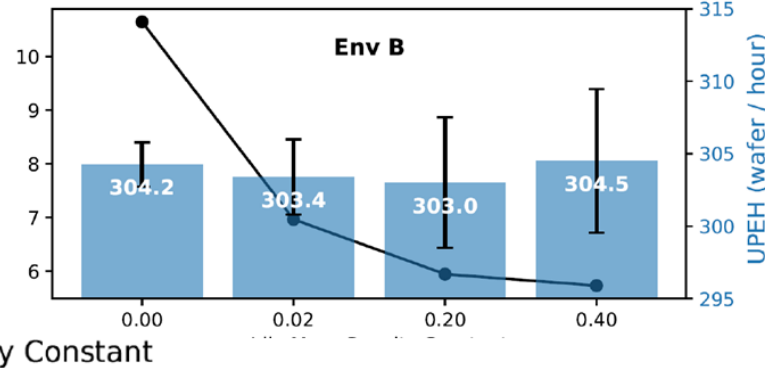
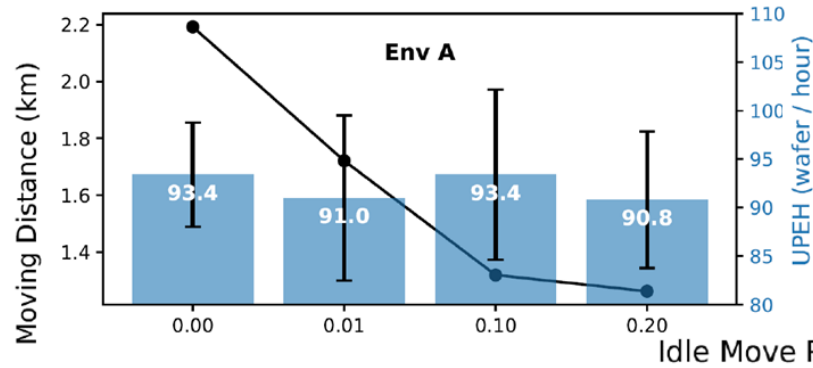
UPEH(Unit per Equipment Hour)

Environment	Completion Only	Progress Only	Both Combined
Env A	81 ± 3	91 ± 6	96 ± 5
Env B	52 ± 5	301 ± 2	304 ± 1

## Idle Move Penalty Effect

- Penalizing idle movement reduces total travel distance
- Proper penalty values reduce inefficiency without hurting UPEH

*Combined use of sparse (completion) and dense (progress) rewards leads to optimal throughput*



## Thank you

*UPEH(Unit per Equipment Hour)*

 Project code & details:

[https://github.com/splendidz/ar\\_drl\\_cluster\\_tool](https://github.com/splendidz/ar_drl_cluster_tool)

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